

## 1.0Amp Standard Surface Mounted Rectifiers

**SMAF**


### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
260°C/10 seconds at terminals

### Mechanical Data

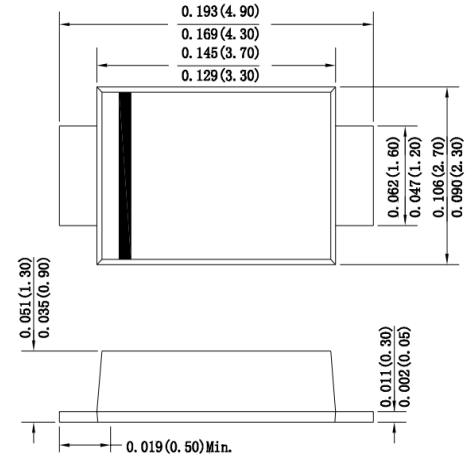
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0014 ounce, 0.038 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	M1F	M2F	M3F	M4F	M5F	M6F	M7F	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	1.0							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	2.0 200							$\mu\text{A}$
Typical junction capacitance (Note1)	$C_J$	15.0							pF
Typical thermal resistance	$R_{QA}$	70.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

## Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

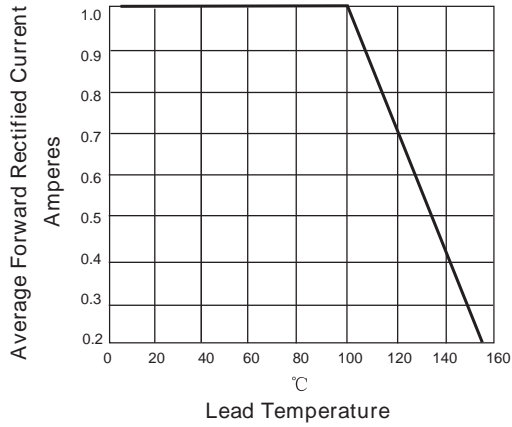


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

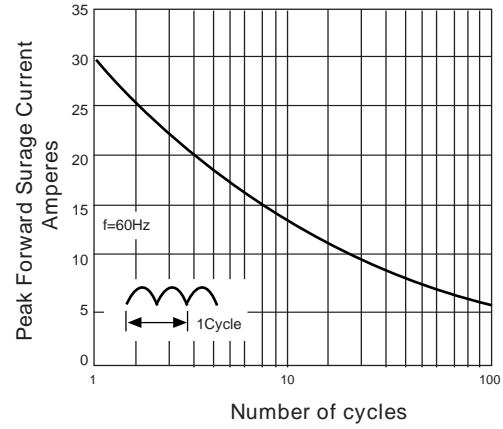


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

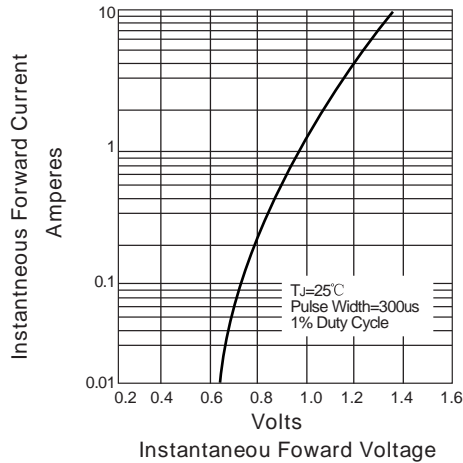
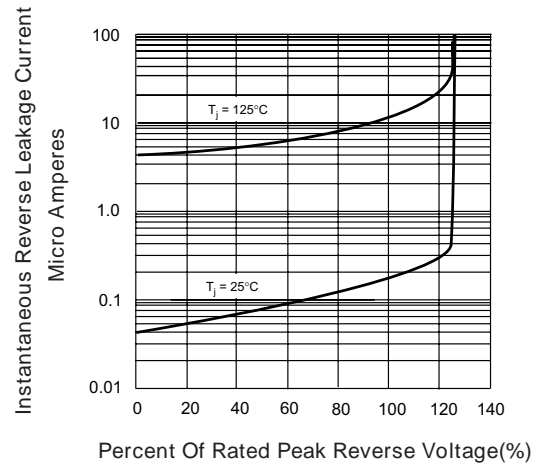
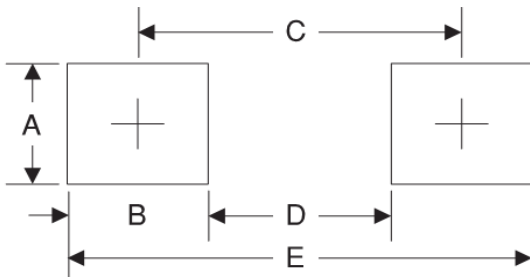


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

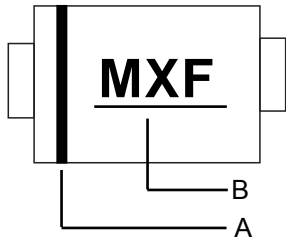


## Suggested Pad Layout



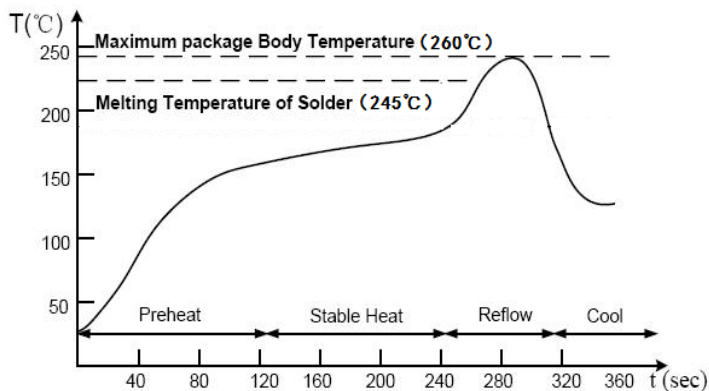
Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.00	0.078
E	5.10	0.200

## Marking



Symbol	Explanation
A	Color Band Denotes Cathode
B	Product Name, X : 1.2.....7

## Suggested Soldering Temperature Profile

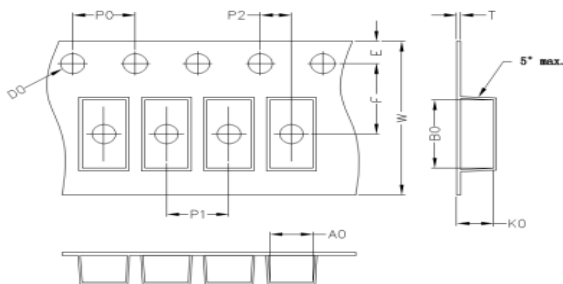


### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.83	4.75	1.42	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	12	0.1

### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	Q'TY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMAF	7'	178	3	180	12	380*200*200	120
	11'	278	7.5	285	15	355*310*310	120